

Figure 1. Example of Wire Bonding Used to Form the Electrical Connections to the Semiconductor Die

WO 2005/062998 PCT/US2004/044097

Semiconductor Die with Solderable Metal System Allowing Direct Surface Mounting to Printed Circuit Boards

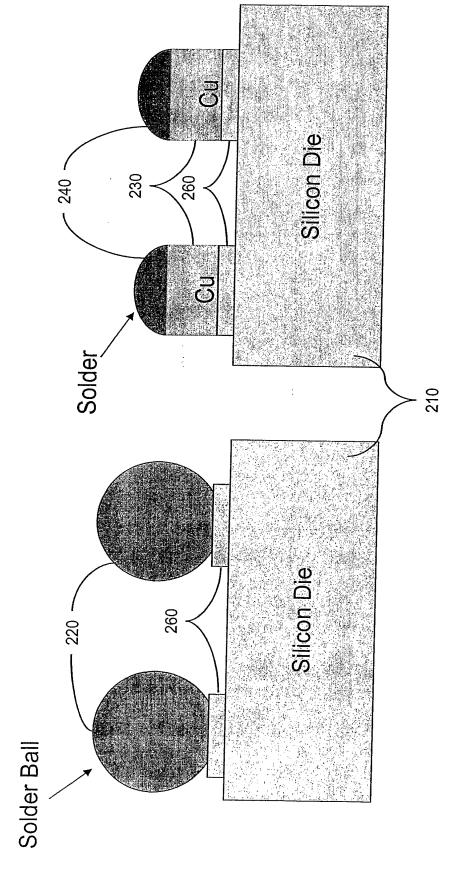


Figure 2. Typical Flip Chip Wafer Bumping Packages

WO 2005/062998 PCT/US2004/044097

Semiconductor Die with Solderable Metal System Allowing Direct Surface Mounting to Printed Circuit Boards

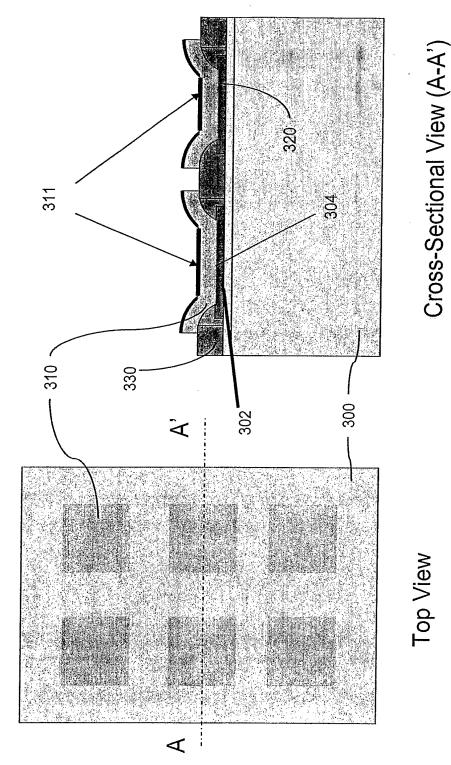


Figure 3. Die with Solderable Metal Contacts for Direct Printed Circuit Board Mounting

WO 2005/062998 PCT/US2004/044097

Semiconductor Die with Solderable Metal System Allowing Direct Surface Mounting to Printed Circuit Boards

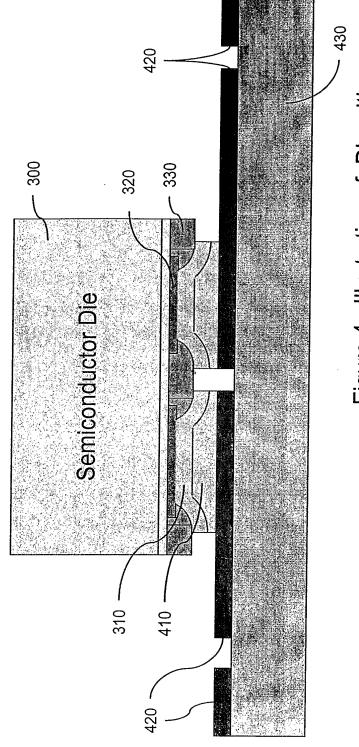


Figure 4. Illustration of Die with Solderable Electrical Contacts Mounted on Printed Circuit Board